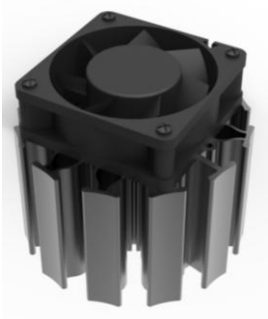
ActiLED ActiLED-F8560 Series Active Heat Sinks Φ85mm for COB Modular Product Brief

Features VS Benefits

* Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
* Thermal resistance range Rth (0.48°C/W).
* Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's:
* Diameter 85mm - Standard height 60.0mm , Other heights on request.
* Extruded from highly conductive aluminum.

2 standard colors - clear anodised - black anodised

Zhaga Book 3 Spot Light Modules Edison ,Xicato ,Bridgelux , Osram ,Citizen ,Lumileds ,Cree , Tridonic , Vossloh-Schwabe ,Seoul ,LG ,Lustrous ,Prolight ,Samung ,SHARP , Luminus .Philips



1) Bridgelux ESS, ESR, Vero 10, Vero 13,Vero 18, V-series;
2) Citizen CLL022-CLU028, CLL032-CLU038,CLL040-CLU048;
3) Cree XLamp CXA13xx, CXA15xx,CXA18xx,CXA25xx,CXA30xx;
4) Philips Fortimo SLM LED engines.
5) Lumileds Luxeon COB's 1203, 1204, 1205,1208,1212,Luxeon K arrays K12, K16;
6) LG Innotek LEMWM18 27W, 24W, 40W,60W,80W;
7) Seoul Semiconductor ZC25, ZC40,ZC60, ZC100 Series;
8) Tridonic TALEXXmodule SLE Modules engines;
9) Edison EdiLex SLM and EdiLex II COB LED engines;
10) OSRAM PrevaLED Core,SOLERIQ P,SOLERIQ E and SOLERIQ S LED engines;
11) Prolight Opto PABS, PABA, PACB, PANA;
12) SHARP Tiger Zenigataand and Mega Zenigata LED engines;
13) Samung COB LC026B,LC033B,LC040BCOB LED engines;
14) Vossloh-Schwabe Vossloh-Schwabe LUGA Shop LED engines;

Order Information

Example:FanLED-F8560-B-#

Example:FanLED-85 1 - 2 - 3

1 Hight (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

Ex.order code - 12

means option 1 and 2 combined

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, a thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

Notes:
- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

Tel:+86-769-39023131
E-fax:+86-(020)28819702 ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
Http://www.mingfatech.com

ActiLED **ActiLED-F8560 Series Active Heat Sinks Φ85mm for COB Modular Product Brief**

The product deta table

Brand	**Mingfa Tech**
Series Name	ActiLED Active heat sink
Seriest Number	ActiLED-F8560
Manufacturing Technology	Aluminum extrusion
Material	AL6063-T5
Color & Finishing	Black Anodized
Certification	CE, ROHS, WEEE
Fan date	Size:60x60x20mm; Electric power:0.48W; Speed:2900RPM ;
Diameter(mm)	Φ85
Heat sink Height(mm)	40.0mm
Max. Lumen	9000lm
Dissipated Power (Ths-amb,50°C)	71.0 W
Thermal Resistance Rth（°C/W)	0.48°C/W
Cooling Surface Area (mm²)	79151.3 mm²
Net Weight (g)	249.9g
Quantity(pcs/CTN)	36 pcs
Modular Types	COB
For Environments	Indoor area
For Lightings	Down lights,Architectural lights
For Application	Retail & Hospitality,Mall & Museums,Office
For LED brands	Bridgelux,BJB,Citizen,Cree,Edison,GE,LG,Lumileds,Lumens,Luminus,Ledil,Nichia,Osram, Philips,Prolight Opto,Samsung,Seoul,Sharp,Tridonic,Vossloh Schwabe,Xicato,Zhaga

* 3D files are avaliable in ParaSolid, STP and IGS on request

* The thermal resistance Rth is determined with a calibrated heat source of 14mm×14mm central placed on the heat sink, Tamb 40° and an open environment. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C
The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power Pd

* Dissipated power Pd. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C
The maximal dissipated power needs to be verified in function of required case temperature Tc or junction temperature Tj and related to the estimated ambient temperature where the light fixture will be placed
Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module

To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL)
Pd - Dissipated power
Pe - Electrical power
ηL = Light effciency of the LED module

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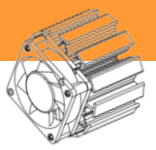
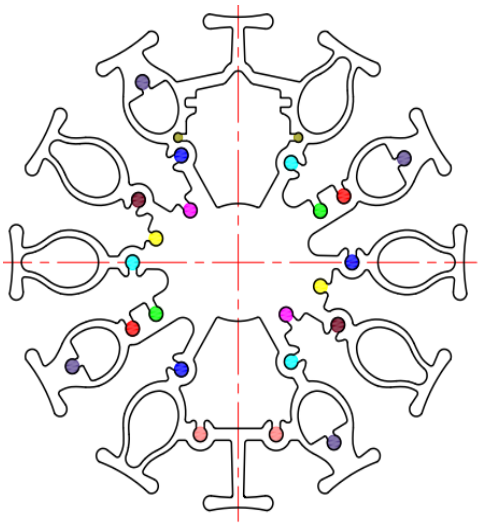
ActiLED

ActiLED-F8560 Series Φ85mm COB Active Heat Sink Drawings

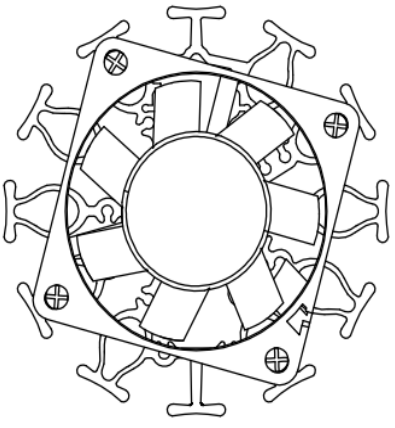


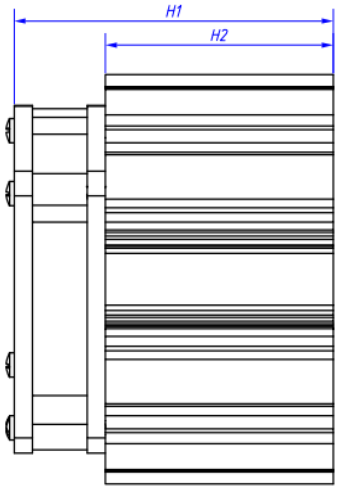
Drawings &Type Selection

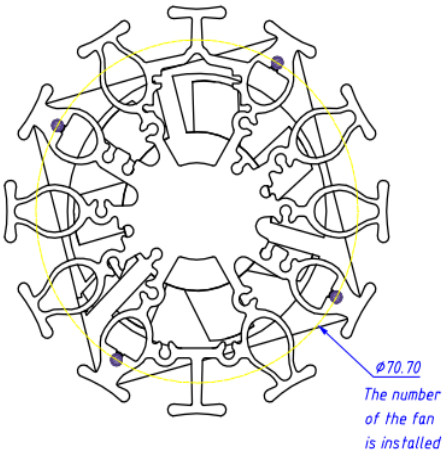


No.	Finish	Mounting hole
A1		25.0mm;2xM3@180°
A2		31.4mm;2xM3@180°
A3		35.0mm;2xM3@180°
A4		39.0mm;3xM3@120°
A5		42.0mm;3xM3@120°
A6		42.5mm;2xM3@180°
A7		45.0mm;2xM3@180°
A8		70.7mm;4xM3@90°
A9		14.0mm;2xM3
A10		22.2mm;2xM2

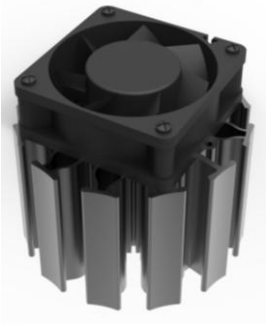
Fan Hole







Product display



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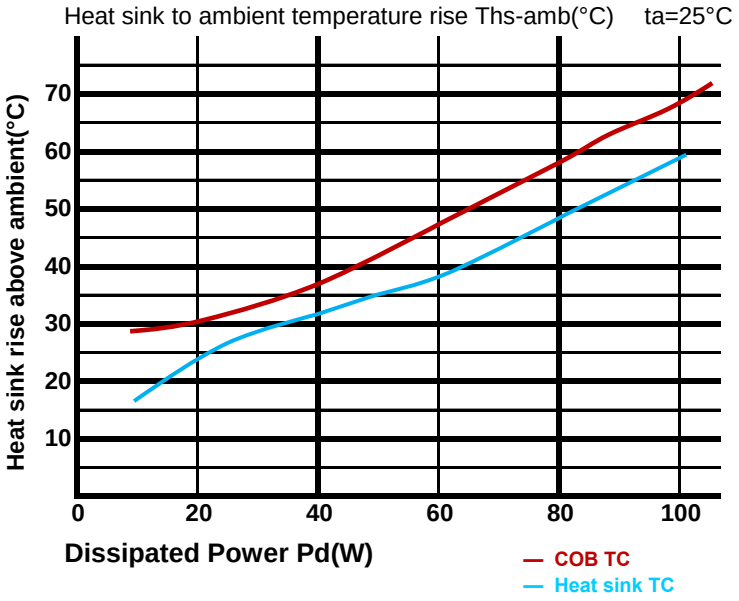
Mingfa TECH

ActiLED-F8560 Series Φ85mm Active Cooling Thermal Data

The thermal data table

ActiLED-F8560 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		ActiLED-F8560	ActiLED-F8560
Dissipated Power Pd(W)	22.7	1.18	26.7
	24.3	1.13	27.5
	34.1	0.85	29.1
	41.8	0.78	33
	56.5	0.65	37.1
	71	0.63	46.2



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

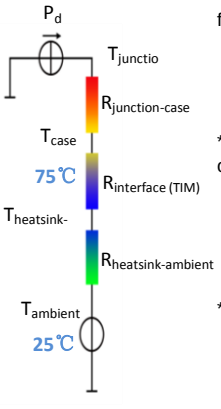
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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